

REFERENCE

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SHARP

OPTO-ANALOG DEVICES DIVISION
ELECTRONIC COMPONENTS GROUP
SHARP CORPORATION

SPECIFICATION

DEVICE SPECIFICATION FOR

MODEL No. PHOTOINTERRUPTER
GP1S094HCZ0F

Specified for _____

Enclosed please find copies of the Specifications which consists of 11 pages including cover.
After confirmation of the contents, please be sure to send back copies of the Specifications
with approving signature on each.

CUSTOMER'S APPROVAL

DATE

BY

PRESENTED

DATE

BY *H.N.*

H. Nakamura,
Department General Manager of
Engineering Dept., III
Opto-Analog Devices Div.
ELECOM Group
SHARP CORPORATION

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Product name : PHOTOINTERRUPTER

Model No. : GP1S094HCZ0F

1. These specification sheets include materials protected under copyright of Sharp Corporation ("Sharp"). Please do not reproduce or cause anyone to reproduce them without Sharp's consent.
2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below. Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) This product is designed for use in the following application areas ;

(• OA equipment • Audio visual equipment • Home appliances
 • Telecommunication equipment (Terminal) • Measuring equipment
 • Tooling machines • Computers

If the use of the product in the above application areas is for equipment listed in paragraphs (2) or (3), please be sure to observe the precautions given in those respective paragraphs.

- (2) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as ;

(• Transportation control and safety equipment (aircraft, train, automobile etc.)
 • Traffic signals • Gas leakage sensor breakers • Rescue and security equipment
 • Other safety equipment

- (3) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as ;

(• Space equipment • Telecommunication equipment (for trunk lines)
 • Nuclear power control equipment • Medical equipment

- (4) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above three paragraphs.

3. Please contact and consult with a Sharp sales representative for any questions about this product.

GP1S094HCZ0F REFERENCE

1. Application

This specification applies to the outline and characteristics of transmissive type photointerrupter; Model No. GP1S094HCZ0F.

2. Outline : Refer to the attached drawing No. CY10532i02.

3. Ratings and characteristics : Refer to the attached sheet, Page 5, 6.

4. Reliability : Refer to the attached sheet, Page 7.

5. Outgoing inspection : Refer to the attached sheet, Page 8.

6. Supplements

6.1 Parts : Refer to the attached sheet, Page 9.

6.2 Packing : Refer to the attached drawing No. CY10533i09.

6.3 ODS materials

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methyl chloroform)

6.4 Specified brominated flame retardants

Specified brominated flame retardants (PBB and PBDE) are not used in this device at all.

6.5 Compliance with each regulation

6.5.1 The RoHS directive(2002/95/EC)

This product complies with the RoHS directive(2002/95/EC).

Object substances: mercury, lead, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE)

6.5.2 Content of six substances specified in Management Methods for Control of Pollution Caused by Electronic Information Products Regulation (Chinese : 电子信息产品污染控制管理办法).

Category	Toxic and hazardous substances					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent chromium (Cr ⁶⁺)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Photointerrupter	✓	✓	✓	✓	✓	✓

✓ : indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard .

6.6 Product mass : Approx. 85mg

7. Notes

1) Circuit design

In circuit designing, make allowance for the degradation of the light emitting diode output that results from long continuous operation. (50% degradation/5 years)

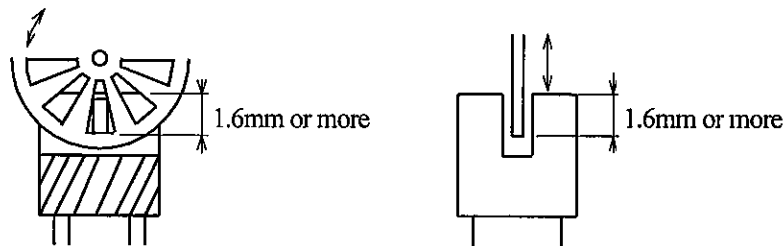
2) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

3) Position of opaque board

Opaque board shall be installed at place 1.6mm or more from the top of elements.

(Example)



4) Soldering

To solder onto lead pins, solder at the position of 1mm or more from the package's bottom at 260°C for 5 s or less.

Please don't bend lead pins from the root of package when soldering.

And please take care not to let any external force exert on lead pins.

Please don't do soldering with preheating, and please don't do soldering by reflow.

5) Cleaning

Cleaning shall carry out as below items to avoid keeping solvent, solder and flux on the device.

- (1) Solvent cleaning : Solvent temperature 45°C or less, Immersion for 3 min or less
- (2) Ultrasonic cleaning : Please don't carry out ultrasonic cleaning.
- (3) The cleaning shall be carried out with solvent below.

Solvent : Ethyl alcohol, Methyl alcohol

6) Lead pin

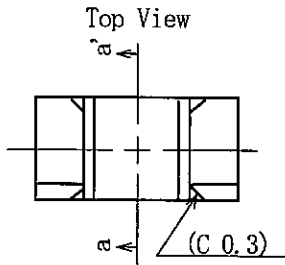
Lead terminals of this product are tin copper alloy plated. Before usage, please evaluate solderability with actual conditions and confirm. And the uniformity in color for the lead terminals are not specified.

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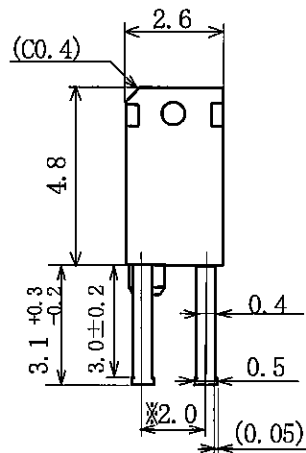
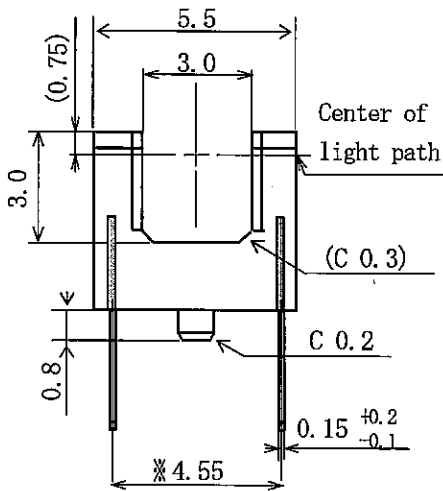
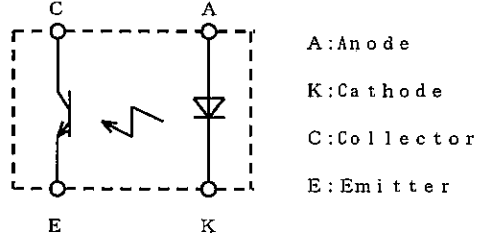
2. Outline Dimensions (Drawing No. CY10532i02)

Scale : 5/1

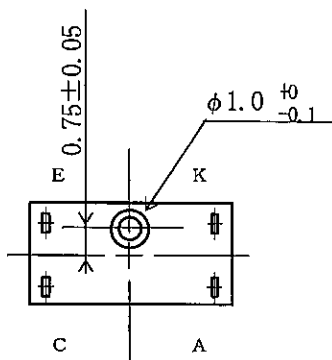
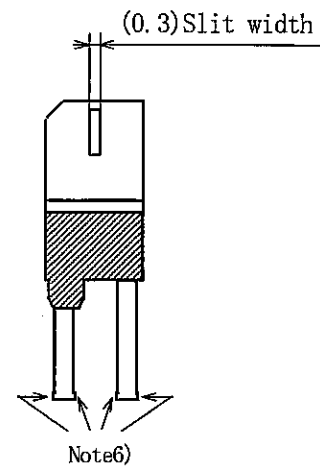
Unit : 1/1mm



Circuit Diagram : Top View



a-a' section



Note

- 1) Unspecified tolerance shall be ± 0.2 .
- 2) Dimensions in parenthesis are shown for reference.
- 3) The dimensions indicated by \times refer to the those measured from the lead base.
- 4) The dimensions shown do not include those of burrs. Burr's dimensions shall be 0.15 MAX..
- 5) The lead may be exposed at the shaded portion.
- 6) This portion has no SnCu plating.

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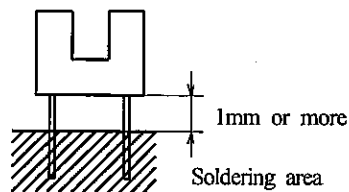
3. Ratings and characteristics

3.1 Absolute maximum ratings

 $T_a=25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_c	20	mA
	Collector power dissipation	P_c	75	mW
Total power dissipation		P_{tot}	100	mW
Operating temperature		T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature		T_{stg}	-40 to +100	$^\circ\text{C}$
* Soldering temperature		T_{sol}	260	$^\circ\text{C}$

* Soldering time : 5 s or less

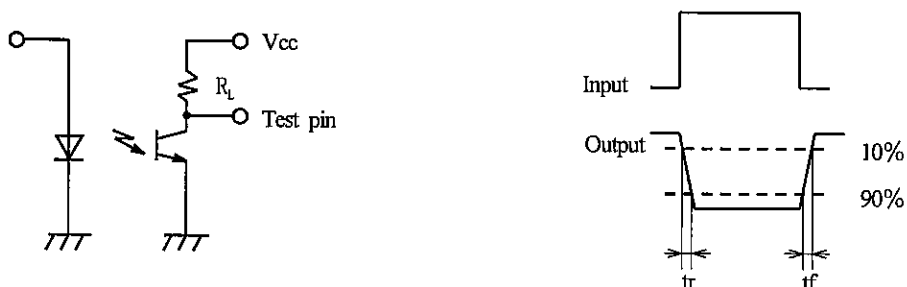


3.2 Electro-optical characteristics

 $T_a=25^\circ\text{C}$

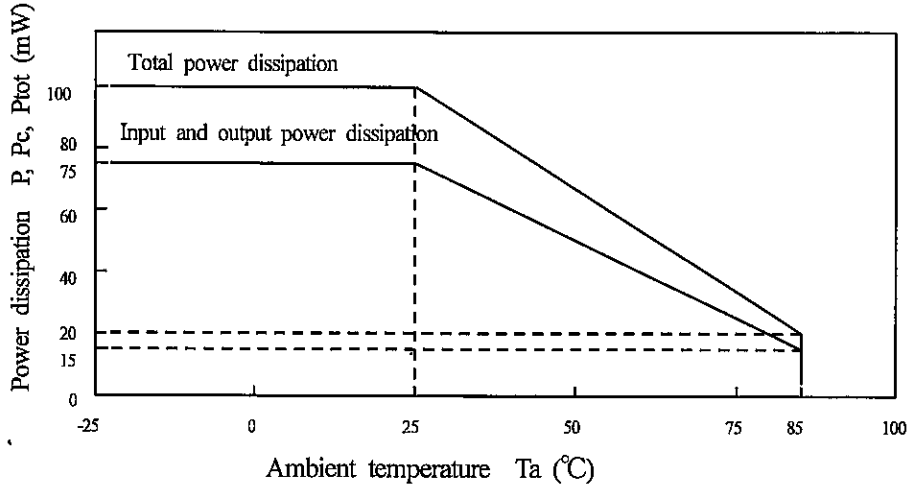
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage	V_F	$I_F=20\text{mA}$	-	1.2	1.4	V	
	Reverse current	I_R	$V_R=3\text{V}$	-	-	10	μA	
Output	Collector dark current	I_{CEO}	$V_{CE}=20\text{V}$	-	-	100	nA	
Transfer characteristics	Collector current	I_c	$V_{CE}=5\text{V}, I_F=5\text{mA}$	40	-	400	μA	
	Response time	(Rise)	t_r	$V_{CE}=5\text{V}, I_c=100\mu\text{A}$ $R_L=1\text{k}\Omega$	-	50	150	μs
		(Fall)	t_f		-	50	150	μs
	Collector-emitter saturation voltage		$V_{CE(sat)}$	$I_F=10\text{mA}, I_c=40\mu\text{A}$	-	-	0.4	V

(Test circuit for response time)

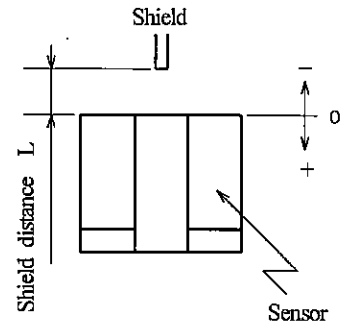
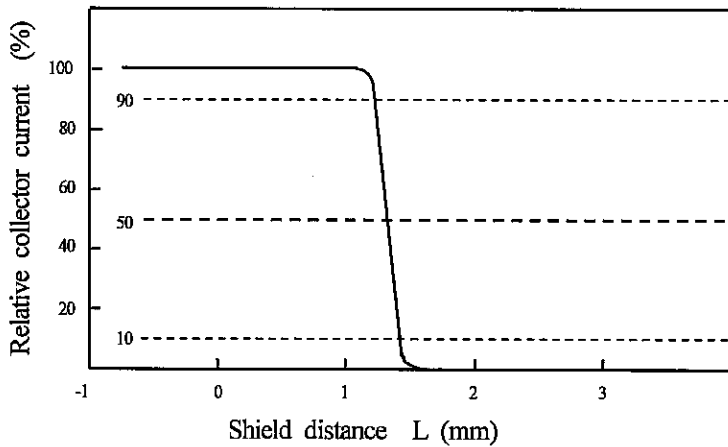


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Power dissipation vs. ambient temperature

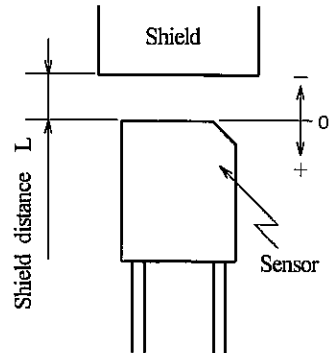
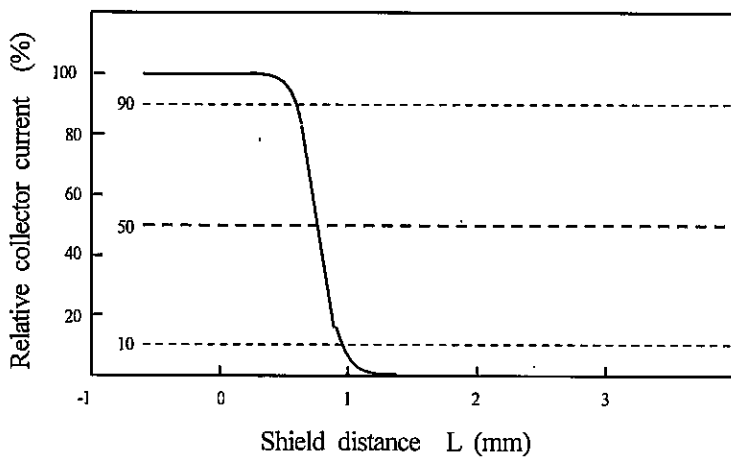


Relative collector current vs. shield distance 1 (Reference value)



Test condition
 $I_F=5.0\text{mA}$
 $V_{CE}=5\text{V}$
 $T_a=25^\circ\text{C}$

Relative collector current vs. shield distance 2 (Reference value)



Test condition
 $I_F=5.0\text{mA}$
 $V_{CE}=5\text{V}$
 $T_a=25^\circ\text{C}$

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4. Reliability

The reliability of products shall satisfy items listed below.

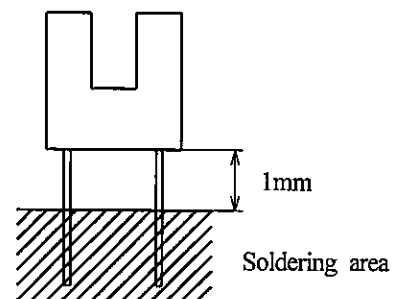
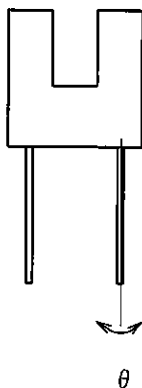
Confidence level : 90%

LTPD : 10 or 20

Test Items	Test Conditions	Failure Judgement Criteria	Samples (n)
			Defective (c)
Temperature cycling	1 cycle -40°C to +100°C (30min) (30min) 20 cycles test	$I_R \geq U \times 2$ $I_{CEO} \geq U \times 2$ $V_F \geq U \times 1.2$ $I_c \leq L \times 0.8$ U: Upper specification limit L: Lower specification limit	n=22, c=0
humidity storage	+60°C, 90%RH, 500h		n=22, c=0
High temp. storage	+100°C, 500h		n=22, c=0
Low temp. storage	-40°C, 500h		n=22, c=0
Operation life	$I_F=20\text{mA}$, $T_a=25^\circ\text{C}$, 500h		n=22, c=0
Mechanical shock	15km/s ² , 0.5ms 3 times/ $\pm X$, $\pm Y$, $\pm Z$ direction		n=11, c=0
Variable frequency vibration	100 to 2000 to 100Hz/20min 2h/X, Y, Z direction 100m/s ²		n=11, c=0
Terminal strength (Tension)	Weight: 3.0N 30s/each terminal		n=11, c=0
Terminal strength (Bending) *1	Weight: 1.0N 0° →90° →0° →-90° →0 1time bending		n=11, c=0
Soldering heat *2	260°C, 5s Immerse up to 1mm from the bottom face of package.		n=11, c=0
Solderability *2, *3	245°C, 5s Prior disposition: Dip rogin flux. Then immerse up to 1mm from the bottom face of package.	Judgement only appearance Solder shall adhere at less than 95% area of immersed portion of lead.	n=11, c=0

* 1 Terminal bending direction is shown below.

*2 Soldering area is shown below.



*3 The alloy composition of solder used for lead free should be Sn-2.5Ag-1Bi-0.5Cu or Sn-3.0Ag-0.5Cu.
Flux used for precleaning should be equivalent to EC-19S(TAMURA KAKEN CORPORATION).

5. Outgoing inspection

5.1 Inspection items

(1) Electrical characteristics

$V_F, I_R, BV_{ECO}, BV_{CEO}, I_c, I_{CEO}, V_{CE(sat)}$

(2) Appearance

5.2 Sampling method and Inspection level

Defect	Inspection item	Inspection level	AQL (%)
Major defect	Characteristics defect	II	0.065
Minor defect	Defects on appearance except shown above. *	II	0.25

A single sampling plan, normal inspection based on ISO 2859 is applied.

※

{	Crack	...	Visible crack shall be defect.
	Split		
	Chip		
	Scratch		
	The others		

 ... One which affects the electrical characteristics shall be defect.

6. Supplements

6.1 Parts

This product uses the below parts.

6.1.1 Light detector (Quantity : 1)

Type	Material	Maximum sensitivity (nm)	Sensitivity (nm)	Response time (μ s)
Phototransistor	Silicon (Si)	930	700 to 1200	20

6.1.2 Light emitter (Quantity : 1)

Type	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared light emitting diode (non-coherent)	GaAs	950	0.3

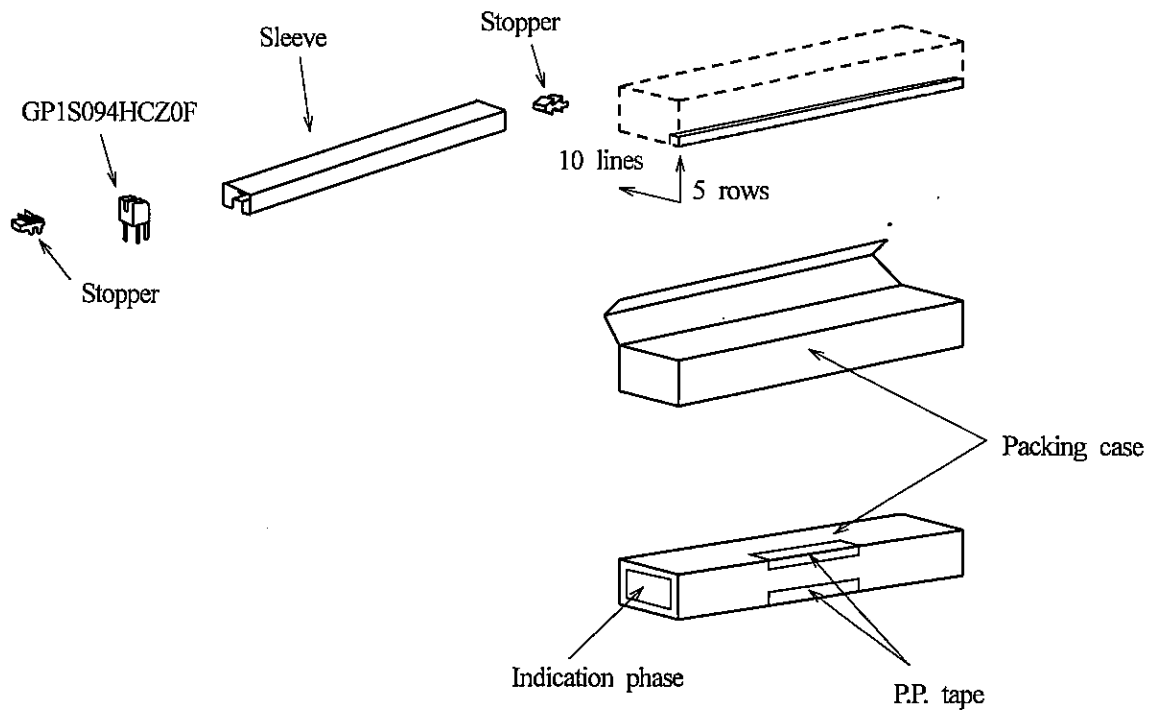
6.1.3 Material

Case	Lead frame	Lead frame plating
Black PPS resin (UL 94V-0)	42 Alloy	SnCu plating

6.1.4 Others

This product shall not be radiation flux proof.

6.2 Package (Drawing No. : CY10533i09)



1) Package materials

Outer package : Packing case (Corrugated cardboard)

Inner package : Sleeve (Polystyrene)

Stopper (Styrene-Elastomer)

2) Packaging numbers

MAX. 100 pieces per sleeve

MAX. 5,000 pieces per case

3) Package specifications

Arranges in 5 rows in 10 lines of sleeves containing GP1S094HCZ0F into the outer case.

Closes the lid of outer case and seals with P.P. tapes.

4) Indication items

The contents of the carton indication conforms to EIAJ C-3 and the following items are indicated.

Model No., Internal production control name, Quantity, Packing date, Corporate name, Country of origin

5) Regular packing mass

(Excluding fractions, however above packing material, packing count, packing style)

- Approx. 970g